

Please amend claim 2 as follows:

1               2. (Amended) A flexible wiring board  
2 comprising:

3               an insulating film having at least one  
4 principal surface;

5               a [principal] printed conductive circuit layer  
6 formed at specified areas on said at least one principal  
7 surface of said insulating film,

8               a metallic layer formed on the printed  
9 conductive circuit layer, said metallic layer having  
10 lands;

11              an insulating layer formed on said metallic  
12 layer said insulating having openings exposing said  
13 lands, and

14              a copper laminated polyimide board disposed in  
15 connection with said lands for soldering.

[Please amend claim 3 as follows:]

1               3. (Amended) A flexible wiring board  
2 comprising:

3               an insulating [surface]film having a curved  
4 portion and at least one principal surface;

5               a printed conductive circuit layer formed at  
6   specified areas on said at least one principal surface of  
7   said insulating film,

8               a first insulating layer formed on at least the  
9   [bent area]curved portion of said insulating film covered  
10 by said printed conductive circuit layer,

11              a metallic layer formed on said printed  
12 conductive circuit layer, and

13              a second insulating layer formed on specified  
14 areas of said metallic layer.

[ Please amend claim 4 as follows: ]

1               4. (Amended) A flexible wiring board  
2 comprising:

3               an insulating film having at least one  
4 principal surface[, said insulating film having at least  
5 one bent area forming a cavity];

6               a printed conductive circuit layer formed at  
7 specified areas on said at least one principal surface of  
8 said insulating film said conductive circuit layer having  
9 at least one cavity exposing said insulating film,

10              a metallic layer formed on said printed  
11 conductive circuit layer, said metallic layer exposing  
12 said cavity and having one or more connecting terminals,

13               an insulating layer formed on said metallic  
14       layer, said insulating layer having openings exposing  
15       said connecting terminals and said cavity, and

16               a reinforcement plate disposed [in said cavity  
17       formed by] on a portion of a surface of said insulating  
18       film.

Please amend claim 16 as follows:

1               ~~16.~~ (Amended) A flexible wiring board  
2       comprising:

3               an insulating film having at least one  
4       principal surface;

5               a first printed conductive circuit layer formed  
6       at specified areas on said at least one principal surface  
7       of said insulating film,

8               a first metallic layer formed on said first  
9       printed conductive circuit layer, said metallic layer  
10      having through-hole lands and external connecting  
11      terminals;

12               [an] a first flexible insulating layer formed on  
13       said insulating film and on said first metallic layer,  
14       said insulating layer having holes exposing said through-  
15       hole lands and exposing said external connecting  
16       terminals;

17               a second printed conductive circuit layer  
18       formed on said insulating layer in connection with said  
19       through-hole lands, and

20                   a second metallic layer formed on said second  
21       printed conductive circuit layer.

[ Please amend claim 17 as follows: ]

1                   ~~13.~~ (Amended) The flexible wiring board  
2       according to Claim ~~16~~, which comprises:

3                   a second insulating layer formed [on said  
4       insulating layer and] on said [the] second metallic  
5       layer, said second insulating layer having openings  
6       exposing said through-hole lands and said external  
7       connecting terminals,

8                   a third printed conductive circuit layer formed  
9       on said second insulating layer in connection with said  
10      through-hole lands, and

11                  a third metallic layer formed on said third  
12       printed conductive circuit layer.

[ Please add new claim 30 as follows:

1                   ~~14.~~ (Newly added) A flexible wiring board  
2       having:

3                   an insulating film having at least one  
4       principal surface;

5                   a conductive circuit layer formed at specified  
6       areas on said at least one principal surface;